16. (Amended) The integrated circuit chip package of claim 15, wherein the mask openings have a first dimension and a second dimension.

17. (Amended) The integrated circuit chip package of claim 16, wherein the first dimension of the mask openings is greater than the second dimension of the mask openings.

18. (Amended) The integrated circuit chip package of claim 16, wherein the first dimension of the mask openings is selectively oriented on the substrate in the direction of highest stress within each interconnection.

19. (Original) The integrated circuit chip package of claim 14, wherein the interconnections have a combination of mask-defined and pad-defined solder joint profiles.

20. (Twice Amended) A substrate having a plurality of conductive pads and a mask thereon, wherein the mask has a plurality of openings having a first dimension larger than a diameter of the conductive pad, and a second dimension smaller than the diameter of the conductive pad, and wherein the first dimension is oriented in the direction of highest stress within interconnections formed within the openings of the mask.

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21. (Original) The substrate of claim 20, wherein the conductive pads are circular.

22. (Original) The substrate of claim 20, wherein the first dimension of the openings is greater than the second dimension of the openings.

24. (Amended) An integrated circuit mask having a plurality of elongated non-circular openings therein, wherein the openings have a first dimension greater than a second dimension, such that the first dimension of the openings coincides with the direction of the highest stress within interconnections formed by the openings.

25. (Original) The integrated circuit mask of claim 24, wherein the mask comprises a non-wettable material.

REMARKS

Claims 1-26 are pending in this application. Claims 1-13 have been withdrawn from consideration. By this amendment the specification and claims 14-18 and 20 have been amended, and claims 23 and 26 has been canceled. Reconsideration and allowance in view of the amendments and the following remarks are